

ABSTRACT OF THE DISCLOSURE

A semiconductor package mainly comprises a substrate unit and a chip. The chip is electrically connected to the substrate unit. The substrate unit includes an upper surface, a lower surface and a side surface. A plurality of circuit traces are formed on the upper surface and a plurality of contacts are formed on the side surface, wherein the contacts are electrically connected to the circuit traces. Besides, a plurality of solder balls are formed on the contacts in order to transmit the signals from chip to outside through the substrate unit, the contacts and the solder balls. Furthermore, a semiconductor package module will be formed by electrically connecting the semiconductor packages with each other through solder balls and a module substrate, and mounting the semiconductor packages with each other through an adhesive layer. In addition, a method for manufacturing the semiconductor package is disclosed.